



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





### GENERAL DESCRIPTION

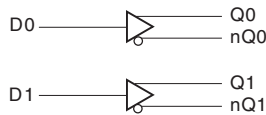


The ICS853L022 is a Dual LVCMOS / LVTTTL-to-Differential 3.3V LVPECL translator and a member of the HiPerClocks™ family of High Performance Clocks Solutions from ICS. The ICS853L022 has single ended clock inputs. The single ended clock input accepts LVCMOS or LVTTTL input levels and translate them to LVPECL levels. The small outline 8-pin TSSOP package makes this device ideal for applications where space, high performance and low power are important.

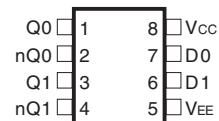
### FEATURES

- 2 differential LVPECL outputs
- LVCMOS/LVTTTL clock inputs
- Output frequency: 350MHz (typical)
- Part-to-part skew: 400 (maximum)
- Propagation Delay: 450ps (typical)
- Additive phase jitter, RMS: 0.03ps (typical)
- LVPECL mode operating voltage supply range:  
 $V_{CC} = 3.0V$  to  $3.8V$ ,  $V_{EE} = 0V$
- ECL mode operating voltage supply range:  
 $V_{CC} = 0V$ ,  $V_{EE} = -3.8V$  to  $-3.0V$
- $-40^{\circ}C$  to  $85^{\circ}C$  ambient operating temperature
- Lead-Free package RoHS compliant

### BLOCK DIAGRAM



### PIN ASSIGNMENT



#### ICS853L022

##### 8-Lead TSSOP, 118 mil

3mm x 3mm x 0.95mm package body

##### G Package

Top View

##### 8-Lead SOIC, 150 mil

3.90mm x 4.90mm x 1.37mm package body

##### M Package

Top View



Integrated  
Circuit  
Systems, Inc.

**ICS853L022**  
DUAL LVCMOS / LVTTTL-TO-DIFFERENTIAL  
3.3V LVPECL TRANSLATOR

**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type	Description
1, 2	Q0, nQ0	Output	Differential output pair. LVPECL interface levels.
3, 4	Q1, nQ1	Output	Differential output pair. LVPECL interface levels.
5	V <sub>EE</sub>	Power	Negative supply pin.
6	D1	Input	LVCMOS / LVTTTL clock input.
7	D0	Input	LVCMOS / LVTTTL clock input.
8	V <sub>CC</sub>	Power	Positive supply pin.



### ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $V_{CC}$	4.6V (LVPECL mode, $V_{EE} = 0$ )
Negative Supply Voltage, $V_{EE}$	-4.6V (ECL mode, $V_{CC} = 0$ )
Inputs, $V_I$ (LVPECL mode)	-0.5V to $V_{CC} + 0.5V$
Inputs, $V_I$ (ECL mode)	0.5V to $V_{EE} - 0.5V$
Outputs, $I_O$	
Continuous Current	50mA
Surge Current	100mA
Operating Temperature Range, $T_A$	-40°C to +85°C
Storage Temperature, $T_{STG}$	-65°C to 150°C
Package Thermal Impedance, $\theta_{JA}$ (Junction-to-Ambient)	101.7°C/W (0 m/s) TSSOP 112.7°C/W (0 lfpm) SOIC

**NOTE:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 2A. POWER SUPPLY DC CHARACTERISTICS,  $V_{CC} = 3.0V$  TO  $3.8V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{CC}$	Positive Supply Voltage		3.0	3.3	3.8	V
$I_{EE}$	Power Supply Current				30	mA

**TABLE 2B. LVCMOS/LVTTTL DC CHARACTERISTICS,  $V_{CC} = 3.0V$  TO  $3.8V$ ;  $V_{EE} = 0V$**

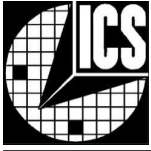
Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage		$0.7 * V_{CC}$			V
$V_{IL}$	Input Low Voltage				$0.3 * V_{CC}$	V
$I_{IH}$	Input High Current	$V_{CC} = V_{IN} = 3.8V$			100	$\mu A$
$I_{IL}$	Input Low Current	$V_{CC} = 3.8V, V_{IN} = 0V$			-0.6	mA

**TABLE 2C. LVPECL DC CHARACTERISTICS,  $V_{CC} = 3.3V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1	2.175	2.275	2.38	2.225	2.295	2.37	2.295	2.33	2.365	V
$V_{OL}$	Output Low Voltage; NOTE 1	1.405	1.545	1.68	1.425	1.52	1.615	1.44	1.535	1.63	V

Output parameters vary 1:1 with  $V_{CC}$ .  $V_{CC}$  can vary 3.8V to 3.0V.  
NOTE 1: Outputs terminated with 50 $\Omega$  to  $V_{CC} - 2V$ .





**TABLE 2D. ECL DC CHARACTERISTICS,  $V_{CC} = 0V$ ;  $V_{EE} = -3.8V$  TO  $-3.0V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1	-1.125	-1.025	-0.92	-1.075	-1.005	-0.93	-1.005	-0.97	-0.935	V
$V_{OL}$	Output Low Voltage; NOTE 1	-1.895	-1.755	-1.62	-1.875	-1.78	-1.685	-1.86	-1.765	-1.67	V
$V_{PP}$	Peak-to-Peak Input Voltage	150	800	1200	150	800	1200	150	800	1200	mV

Output parameters vary 1:1 with  $V_{CC}$ .

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CC} - 2V$ .

**TABLE 3. AC CHARACTERISTICS,  $V_{CC} = 0V$ ;  $V_{EE} = -3.8V$  TO  $-3.0V$  OR  $V_{CC} = 3.0V$  TO  $3.8V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{MAX}$	Output Frequency		350			350			350		MHz
$tp_{LH}$	Propagation Delay, Low to High; NOTE 1	300	525	750	300	450	600	300	450	600	ps
$t_{sk(o)}$	Output Skew; NOTE 2, 4		10	45		10	45		10	45	ps
$t_{sk(pp)}$	Part-to-Part Skew; NOTE 3, 4			225			225			225	ps
$t_{jit}$	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter section		0.03			0.03			0.03		ps
$t_R/t_F$	Output Rise/Fall Time 20% to 80%	100	325	550	100	325	550	100	325	550	ps

All parameters are measured  $\leq 350MHz$  unless otherwise noted.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

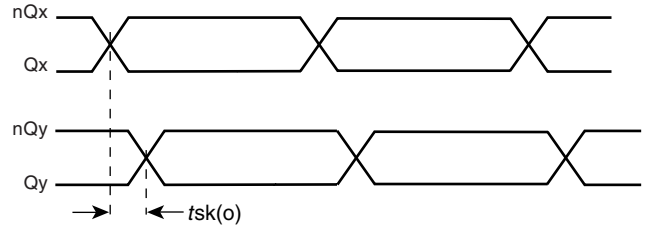
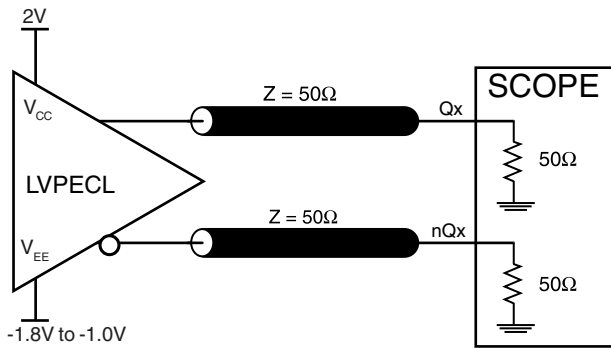
NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

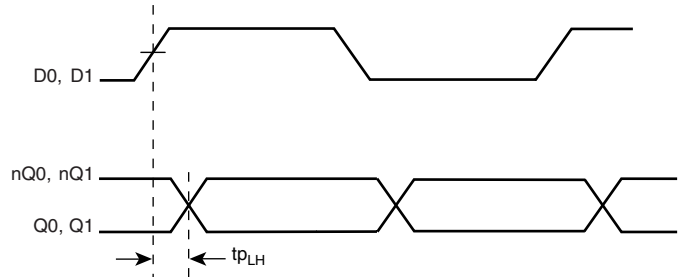
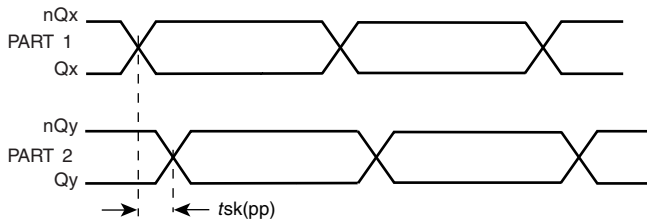


## PARAMETER MEASUREMENT INFORMATION



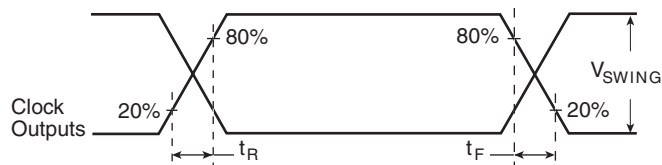
**OUTPUT LOAD AC TEST CIRCUIT**

**OUTPUT SKEW**



**PART-TO-PART SKEW**

**PROPAGATION DELAY**



**OUTPUT RISE/FALL TIME**



## APPLICATION INFORMATION

### TERMINATION FOR 3.3V LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive

50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 1A and 1B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

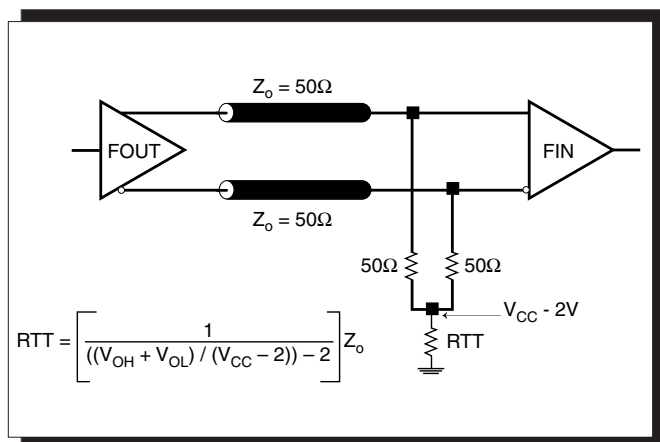


FIGURE 1A. LVPECL OUTPUT TERMINATION

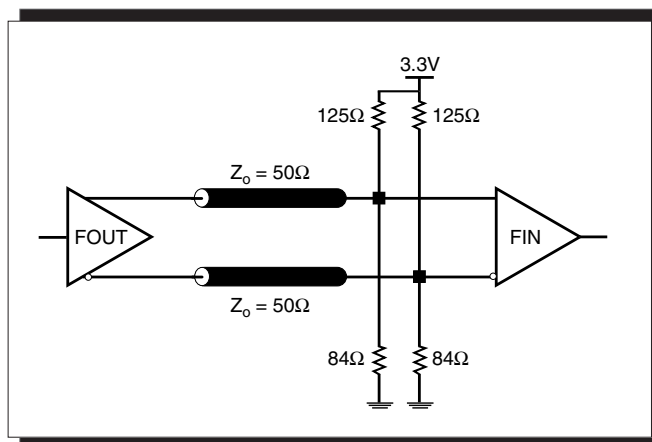


FIGURE 1B. LVPECL OUTPUT TERMINATION



## POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS853L022. Equations and example calculations are also provided.

### 1. Power Dissipation.

The total power dissipation for the ICS853L022 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 3.8V$ , which gives worst case results.

**NOTE:** Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> =  $V_{CC\_MAX} * I_{EE\_MAX} = 3.8V * 30mA = 114mW$
- Power (outputs)<sub>MAX</sub> = **30.94mW/Loaded Output pair**  
If all outputs are loaded, the total power is  $2 * 30.94mW = 61.88mW$

**Total Power**<sub>MAX</sub> (3.8V, with all outputs switching) =  $114mW + 61.88mW = 175.88mW$

### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming a moderate air flow of 1 meters per second and a multi-layer board, the appropriate value is 90.5°C/W per Table 4A below.

Therefore,  $T_j$  for an ambient temperature of 85°C with all outputs switching is:

$85^\circ C + 0.176W * 90.5^\circ C/W = 100.9^\circ C$ . This is below the limit of 125°C.

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

**TABLE 4A. THERMAL RESISTANCE  $\theta_{JA}$  FOR 8-PIN TSSOP, FORCED CONVECTION**

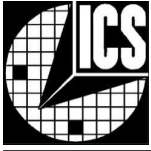
$\theta_{JA}$ by Velocity (Meters per Second)			
	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	101.7°C/W	90.5°C/W	89.8°C/W

**TABLE 4B. THERMAL RESISTANCE  $\theta_{JA}$  FOR 8 LEAD SOIC**

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W

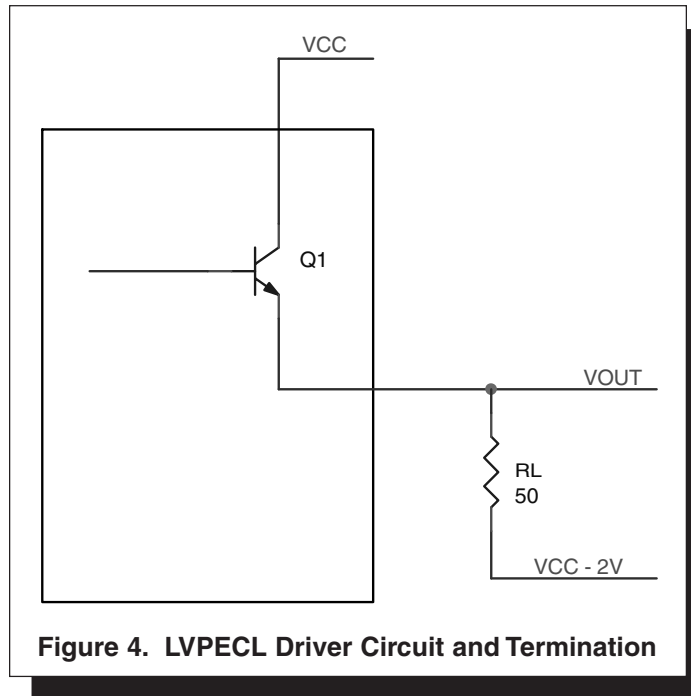
**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.





### 3. Calculations and Equations.

LVPECL output driver circuit and termination are shown in Figure 4.



**Figure 4. LVPECL Driver Circuit and Termination**

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of  $V_{CCO} - 2V$ .

- For logic high,  $V_{OUT} = V_{OH\_MAX} = V_{CCO\_MAX} - 0.935V$

$$(V_{CC\_MAX} - V_{OH\_MAX}) = 0.935V$$

- For logic low,  $V_{OUT} = V_{OL\_MAX} = V_{CCO\_MAX} - 1.67V$

$$(V_{CCO\_MAX} - V_{OL\_MAX}) = 1.67V$$

$$Pd\_H = [(V_{OH\_MAX} - (V_{CCO\_MAX} - 2V))/R_L] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - 0.935V)/50\Omega] * 0.935V = 19.92mW$$

$$Pd\_L = [(V_{OL\_MAX} - (V_{CCO\_MAX} - 2V))/R_L] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - 1.67V)/50\Omega] * 1.67V = 11.02mW$$

Total Power Dissipation per output pair =  $Pd\_H + Pd\_L = 30.94mW$



## RELIABILITY INFORMATION

**TABLE 5A.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 8 LEAD TSSOP**

$\theta_{JA}$ by Velocity (Meters per Second)			
	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	101.7°C/W	90.5°C/W	89.8°C/W

**TABLE 5B.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 8 LEAD SOIC**

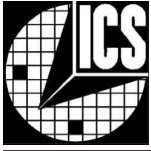
$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

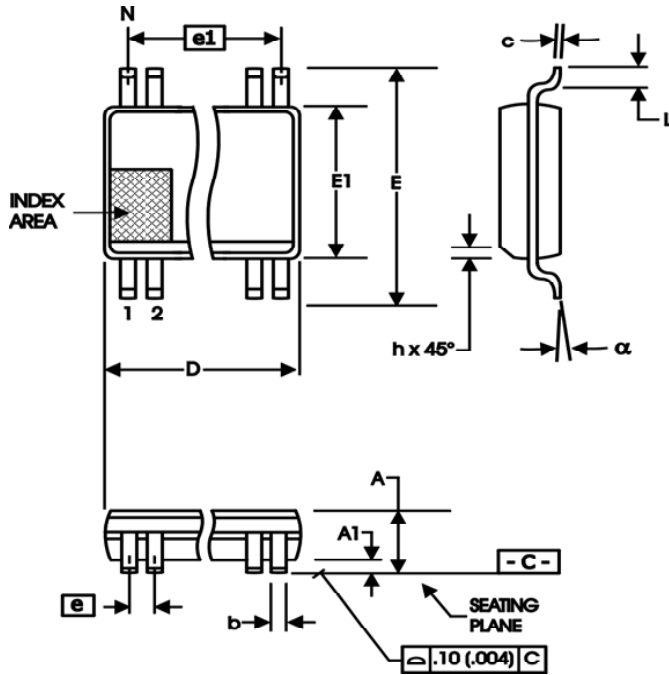
### TRANSISTOR COUNT

The transistor count for ICS853L022 is: 92

Pin compatible with MC100LVELT22



PACKAGE OUTLINE - G SUFFIX FOR 8 LEAD TSSOP



PACKAGE OUTLINE - M SUFFIX FOR 8 LEAD SOIC

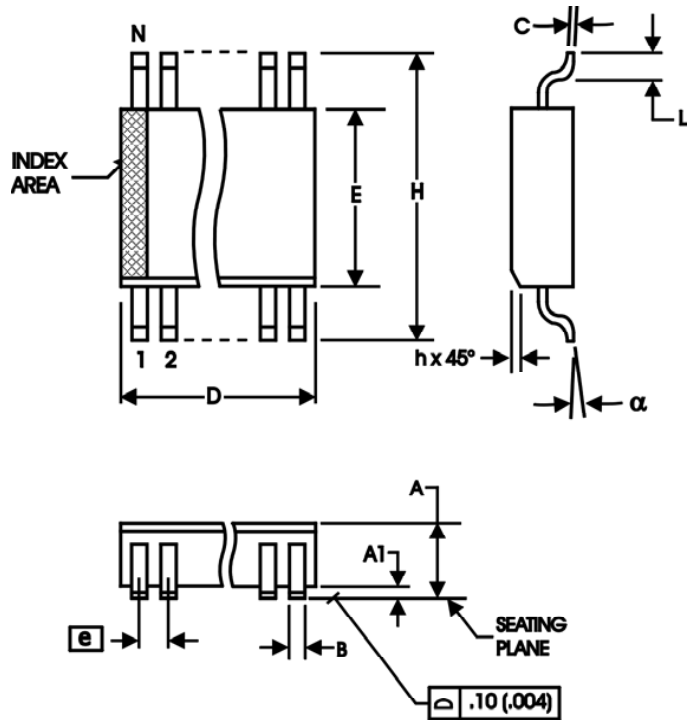


TABLE 6A. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	Minimum	Maximum
N	8	
A	--	1.10
A1	0	0.15
A2	0.79	0.97
b	0.22	0.38
c	0.08	0.23
D	3.00 BASIC	
E	4.90 BASIC	
E1	3.00 BASIC	
e	0.65 BASIC	
e1	1.95 BASIC	
L	0.40	0.80
α	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-187

TABLE 6B. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MINIMUM	MAXIMUM
N	8	
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BASIC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
α	0°	8°

Reference Document: JEDEC Publication 95, MS-012



Integrated  
Circuit  
Systems, Inc.

# ICS853L022

## DUAL LVCMOS / LVTTTL-TO-DIFFERENTIAL 3.3V LVPECL TRANSLATOR

**TABLE 7. ORDERING INFORMATION**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
853L022AG	022A	8 lead TSSOP	tube	-40°C to 85°C
853L022AGT	022A	8 lead TSSOP	2500 tape & reel	-40°C to 85°C
853L022AGLF	L2AL	8 lead "Lead-Free" TSSOP	tube	-40°C to 85°C
853L022AGLFT	L2AL	8 lead "Lead-Free" TSSOP	2500 tape & reel	-40°C to 85°C
853L022AM	53L022A	8 lead SOIC	tube	-40°C to 85°C
853L022AMT	53L022A	8 lead SOIC	2500 tape & reel	-40°C to 85°C
853L022AMLF	53L022AL	8 lead "Lead-Free" SOIC	tube	-40°C to 85°C
853L022AMLFT	53L022AL	8 lead "Lead-Free" SOIC	2500 tape & reel	-40°C to 85°C

The aforementioned trademark, HiPerClockS™ is a trademark of Integrated Circuit Systems, Inc. or its subsidiaries in the United States and/or other countries. While the information presented herein has been checked for both accuracy and reliability, Integrated Circuit Systems, Incorporated (ICS) assumes no responsibility for either its use or for infringement of any patents or other rights of third parties, which would result from its use. No other circuits, patents, or licenses are implied. This product is intended for use in normal commercial and industrial applications. Any other applications such as those requiring high reliability or other extraordinary environmental requirements are not recommended without additional processing by ICS. ICS reserves the right to change any circuitry or specifications without notice. ICS does not authorize or warrant any ICS product for use in life support devices or critical medical instruments.